1OEB

1<u>LE</u> 2

1ERR 3

GND 4

1A1 🛛 5

1A2 🛛 6

V_{CC} []7

1A3 🛛 8

1A4 🛛 9

1A5 🚺 10

GND 🛛 11

1A6 12

1A7 13 1A8 14

2A1 15

2A2 16

2A3 17

GND 18

2A4 🛛 19

2A5 20

2A6 🛛 21

V_{CC} [] 22

2A7 23

2A8 24

GND 25

2ERR 26

20EB 28

2LE 27

SN54ABT16853 . . . WD PACKAGE SN74ABT16853 . . . DGG OR DL PACKAGE (TOP VIEW)

SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997

56 1 1 OEA

55 1 1 CLR

53 GND

52 31B1

51 **1**B2

50 VCC

49**1**1B3

48 **1** 1B4

47 **1** 1B5

46 GND

45 **1**B6

44 🛛 1B7

43 **1**B8

42 **1** 2B1

41 **1** 2B2

40 **1** 2B3

39 GND

38 2B4

37 2B5

36 2B6

35 🛛 V_{CC}

34 2B7

33 **1** 2B8

32 GND

30 2 2 CLR

29 20EA

31 2PARITY

54 | 1PARITY

Members of the Texas Instruments	
<i>Widebus</i> ™ Family	

- State-of-the-Art *EPIC-IIB*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Parity-Error Flag With Parity Generator/Checker
- Latch for Storage of the Parity-Error Flag
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16853 dual 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus, with its corresponding parity bit, the open-collector parity-error (ERR) output indicates whether or not an error in the B data has occurred. The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT16853 provide true data at the outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports
with the ERR flag. The parity-error output can be passed, sampled, stored, or cleared from the latch using the
latch-enable (LE) and clear (CLR) control inputs. When both OEA and OEB are low, data is transferred from
the A bus to the B bus, and inverted parity is generated. Inverted parity is a forced error condition that gives the
designer more system diagnostic capability.

Com.G

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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description (continued)

The SN54ABT16853 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16853 is characterized for operation from -40°C to 85°C.

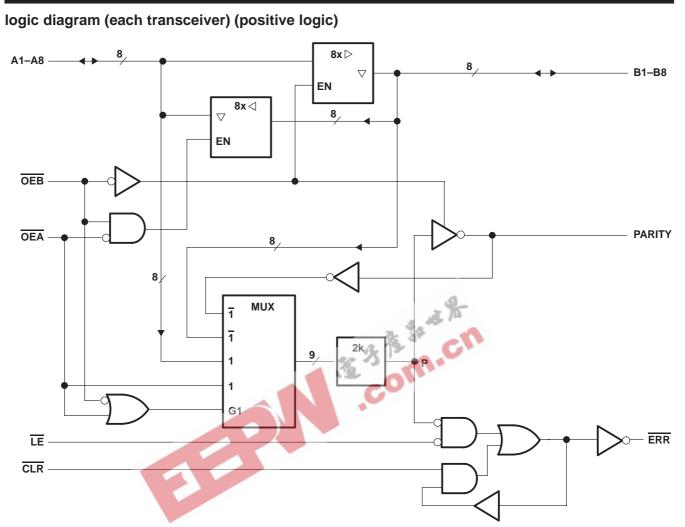
		11	NPUTS				OUTPU	t and I/O		
OEB	OEA	CLR	LE	ΑΙ Σ ΟF Η	ΒΙ† Σ OF Η	A B PARITY		ERR‡	FUNCTION	
L	Н	х	х	Odd Even	NA	NA	А	L H	NA	A data to B bus and generate parity
Н	L	х	L	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity
Н	L	Н	Н	NA	Х	Х	NA	NA	NC	Store error flag
Х	Х	L	Н	Х	Х	Х	NA	NA	Н	Clear error-flag register
		Н	Н	Х					NC	
Н	Н	L X X	H L L	X L Odd H Even	x	z	Z	Z	H	Isolation§ (parity check)
L	L	х	Х	Odd Even	NA	NA	A 3	н L	NA	A data to B bus and generate inverted parity

 * Summation of high-level inputs includes PARITY along with Bi inputs.
* Output states shown assume ERR was previously high.
§ In this mode, ERR (when clocked) shows inverted parity of the A bus. 4

1



SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997



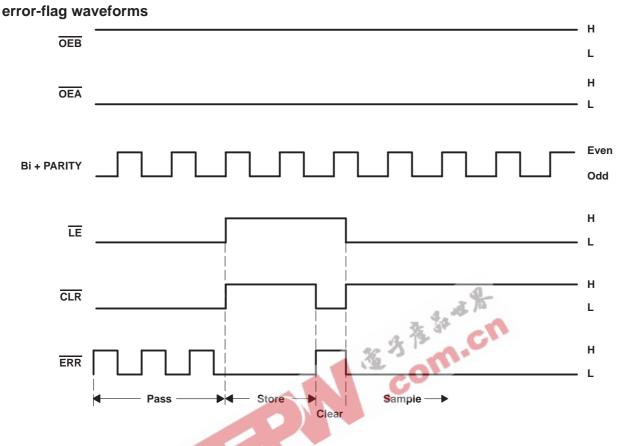
ERROR-FLAG FUNCTION TABLE

INPU	JTS	INTERNAL TO DEVICE	OUTPUT		FUNCTION	
CLR	LE	POINT P	ERR _{n-1} †	ERK		
		L	х	L	Pass	
	L	Н	^	н	Fass	
		L	Х	L		
н	L	х	L	L	Sample	
		Н	Н	н		
L	Н	Х	Х	Н	Clear	
н	н х		L	L	Store	
п	п	Х	Н	н	Store	

[†] State of ERR before changes at CLR, LE, or point P



SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	
Current into any output in the low state, I _O : SN54ABT16853	
SN74ABT16853	
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DL package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997

recommended operating conditions (see Note 3)

			SN54ABT	16853	SN74ABT	16853	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	M	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0	Vcc	0	VCC	V
VOH	High-level output voltage	ERR		5.5		5.5	V
ЮН	High-level output current	Except ERR	na	-24		-32	mA
IOL	Low-level output current		06	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TEST CO		Т	A = 25°C		SN54AB	Г16853	SN74AB	16853	UNIT	
PA	RAMETER	TEST CO	MIN	түр†	MAX	MIN	MAX	MIN	MAX	UNIT		
VIK		V _{CC} = 4.5 V,	lı =18 mA		1. 12	-1.2	C.	-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5	3	~	2.5					
Vou	All outputs	$V_{CC} = 5 V,$	I _{OH} = -3 mA	3	3.4		3		3		V	
Vон	except ERR	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$		V		2				v	
		VCC = 4.5 V	I _{OH} = -32 mA	2*	2.7				2			
Val		V _{CC} = 4.5 V	I _{OL} = 24 mA		0.25	0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA		0.3	0.55*				0.55	v	
V _{hys}					100			2			mV	
IOH	ERR	V _{CC} = 4.5 V,	V _{OH} = 5.5 V			20		20		20	μΑ	
loff	-	$V_{CC} = 0,$	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100		351		±100	μΑ	
ICEX	Outputs high	$V_{CC} = 5.5 V,$	V _O = 5.5 V			50	4	50		50	μΑ	
L.	Control inputs	V _{CC} = 5.5 V, V _I = V				±1	20	±1		±1	μA	
ł	A or B ports	VCC = 5.5 v, v] = v	CC OL GIVD			±100	00	±100		±100	μΛ	
۱ _{IL}	A or B ports	$V_{CC} = 0,$	V _I = GND			-50	40	-50		-50	μΑ	
10‡		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
IOZH§		V _{CC} =5.5 V,	V _O = 2.7 V			50		50		50	μΑ	
IOZL§		V _{CC} = 5.5 V,	V _O = 0.5 V			-50		-50		-50	μΑ	
		V _{CC} = 5.5 V,	Outputs high		1.5	2		2		2		
ICC	A or B ports	$I_{O} = 0,$	Outputs low		32	40		40		40	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		1	2		2		2		
∆ICC¶		V_{CC} = 5.5 V, One in Other inputs at V_{CC}				50		50		50	μΑ	
Ci	Control inputs	$V_{I} = 2.5 \text{ V or } 0.5 \text{ V}$			3						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5 V			9						рF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at V_{CC} = 5 V.

[‡]Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 \S The parameters IOZH and IOZL include the input leakage current.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} = T _A = 2	⊧ 5 V, 25°C	SN54AB	Г16853	SN74AB1	16853	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
t Dulas duration		LE high or low	8.5		8.5	15	8.5		-	
tw	Pulse duration	CLR low	4		4	35	4		ns	
	Catua tima	A, B, and PARITY before $\overline{\text{LE}}\downarrow$	10		10	2	10			
t _{su}	Setup time	CLR before LE↓	0		9		0		ns	
+.	Hold time	A, B, and PARITY after $\overline{\text{LE}}\downarrow$	0		0		0			
th		CLR after LE↓	0		50		0		ns	

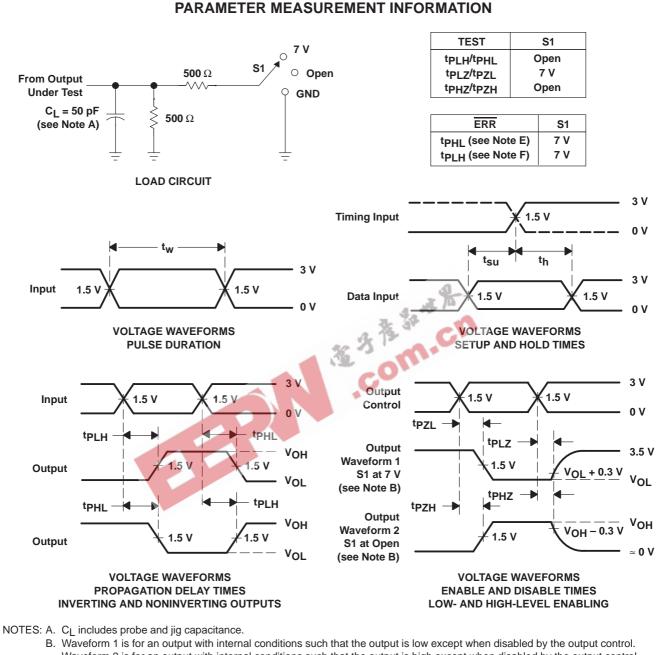
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V T	CC = 5 V, A = 25°C		SN54ABT	16853	SN74AB1	Г16853	UNIT
		(001201)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
^t PHL	AUB	BOIA	2	3.1	3.9	2	4.5	2	4.3	115
^t PLH	A	PARITY	2	4.6	5.9	2	7.3	2	7.1	ns
^t PHL	A or OE	FARILI	2	4.8	6.2	2	7.6	2	7.2	115
^t PLH	CLR	ERR	2	3.7	5.1	2	5.9	2	5.7	ns
^t PZH		A or B	2	3.9	4.9	2	5.8	2	5.6	ns
^t PZL	OE	AUD	2.5	4.3	5.1	2.5	õ 6.2	2.5	6	115
^t PHZ	OE	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
^t PLZ	ÛE	AOIB	1.5	3	3.8	1.5	4.7	1.5	4.3	115
^t PZH		PARITY	2	3.6	5	2	5.8	2	5.7	ns
^t PZL	OE	PARITI	2.5	4.4	5.8	2 .5	6.7	2.5	6.5	115
^t PHZ	OE	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	ns
^t PLZ	OE	FARIT	1.5	2.9	3.7	1.5	4.2	1.5	4.1	115
^t PLH	LE	ERR	2	3.5	4.2	2	5	2	4.8	ns
^t PHL	LE	EKK	2	3.4	4.4	2	5.2	2	4.9	115
^t PLH	A, B, or PARITY	ERR	2	4.5	6.3	2	7.5	2	7.2	ns
tPHL			2	4.8	6.3	2	7.7	2	7.4	115

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SCBS153B - OCTOBER 1992 - REVISED JANUARY 1997



Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpHL is measured at 1.5 V.
- F. tpLH is measured at VOL + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms



6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT16853DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD**: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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